

Full year 17 results

> June 2017



soitec

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- 1 FY'17 highlights
- 2 FY'17 financials
- 3 **Business review: promising prospects in Electronics**
- 4 Outlook
- 5 Appendix

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Soitec: engineered substrates at the heart of everyday life

Data Centers



IoT and wearables



Automotive



Consumer Multimedia



Intensified Challenges



**Outstanding
Performance**



**Longer battery
life**



High reliability



Optimized cost

enabled by Soitec technologies



We deliver
innovative substrates & processes
enabling electronic systems,
creating value for everyday life

Advanced Semiconductor Materials

FY'17 overview (1/2): strengthened balance sheet

**A significant strengthening of the balance sheet
thanks to € 150m equity raised in Q1'17**

Shareholder's
equity
restored

Through 3 reserved
capital increases and a
rights issue

A decisive
realignment
of the
shareholder
structure

CEA Investissement,
NSIG and Bpifrance:
3 strategic partners
each holding 14.5% of
Soitec's share capital

A significant
deleveraging

€ 110m used to repay
bridge loans and
partially buy back
OCEANE bonds

A stronger
cash position
to support
future growth

€ 40m dedicated to
Bernin II capex aimed
at increasing FD-SOI
production capacity

FY'17 overview (2/2): further operating leverage thanks to Electronics business profitable growth

› Solid organic growth and a significant surge in profitability in FY'17

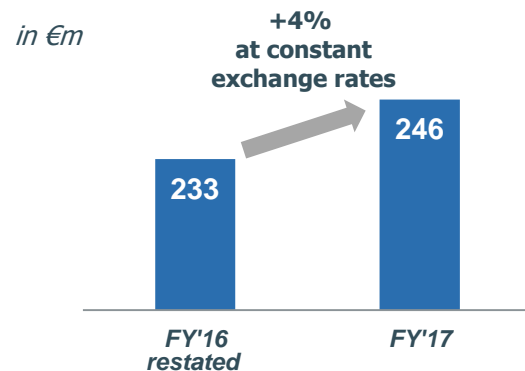
- › Bernin I (200mm) operating at full capacity thanks to the sustained demand in RF-SOI and Power-SOI
- › Bernin II (300mm) still under-utilized but has overcome the decline in PD-SOI with a good pick-up in all other 300mm products (RF-SOI, FD-SOI, Emerging SOI)
- › Higher utilization of production capacity, better productivity and good control over costs translated into a further increase in manufacturing margin

› FY'17, another year of significant developments in the FD-SOI ecosystem

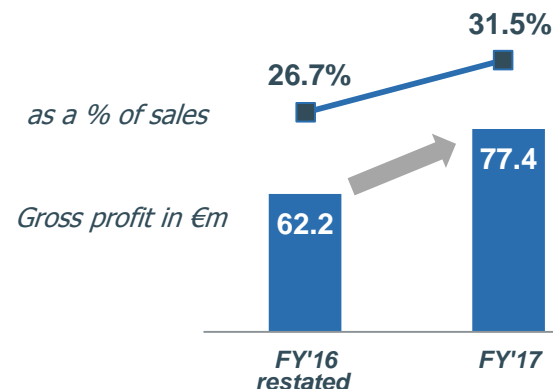
- › First FD-SOI technology-based products launched for applications in automotive and IoT markets
- › GlobalFoundries to invest in 22nm FD-SOI capacity growth in Germany and China + roadmap to 12nm
- › Samsung to extend current 28nm FD-SOI platform for embedded memory and RF + roadmap to 18nm

Substantial improvement in operating profitability achieved in FY'17

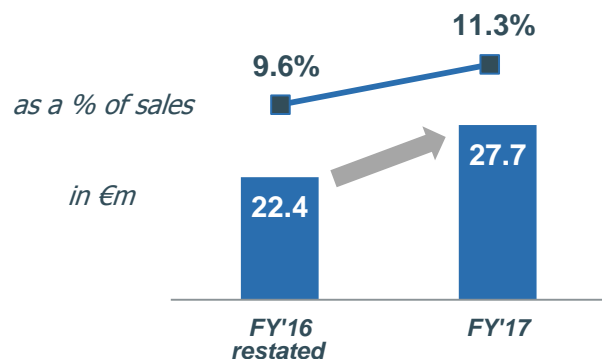
Sales growth (Electronics)



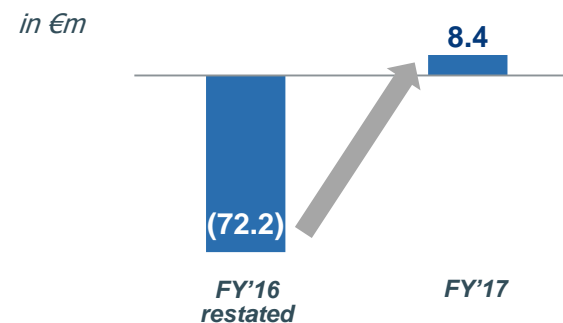
Significant increase in gross margin



Increase in current operating income



Positive net result



The income and expenses related to discontinued operations are directly reported as "Net result from discontinued operations". Down to the line "Net result after tax from continuing operations", the Group consolidated P&L account now exclusively and fully reflects the Electronics activities as well as corporate expenses. The FY'16 financial statements have been restated to ensure comparability with the FY'17 financial statements.

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FY'17: revenue breakdown

In million euros

	FY'16	Q1'17	Q2'17	Q3'17	Q4'17	FY'17	Change vs FY'16	Change at constant FX
200mm wafer sales	170.5	42.7	44.7	47.9	47.2	182.5	+7%	+6%
300mm wafer sales	53.6	11.4	10.7	13.4	21.3	56.7	+6%	+5%
Royalties and IP revenues	9.1	1.4	1.3	1.8	2.0	6.6	(28)%	(29)%
Total sales	233.2	55.4	56.7	63.1	70.5	245.7	+5%	+4%

› 200mm wafer sales up 6% excl. currency impact

- › Sales driven by sustained demand for radio frequency and power electronics applications in the mobile and automotive markets respectively
- › Bernin I production site operating at full capacity with improved productivity, leading to volume increase vs FY'16

› 300mm wafer sales up 5% excl. currency impact thanks to pick-up after low-point reached in Q2'17

- › Negative impact of anticipated decline of the PD-SOI product line
- › As from Q3'17, significant pick-up in other 300mm products: FD-SOI, RF-300mm, Emerging SOI
- › Bernin II production site remains vastly under-utilized pending the rise in RF-300mm demand and mass-market production of FD-SOI

Group consolidated P&L (1/2)

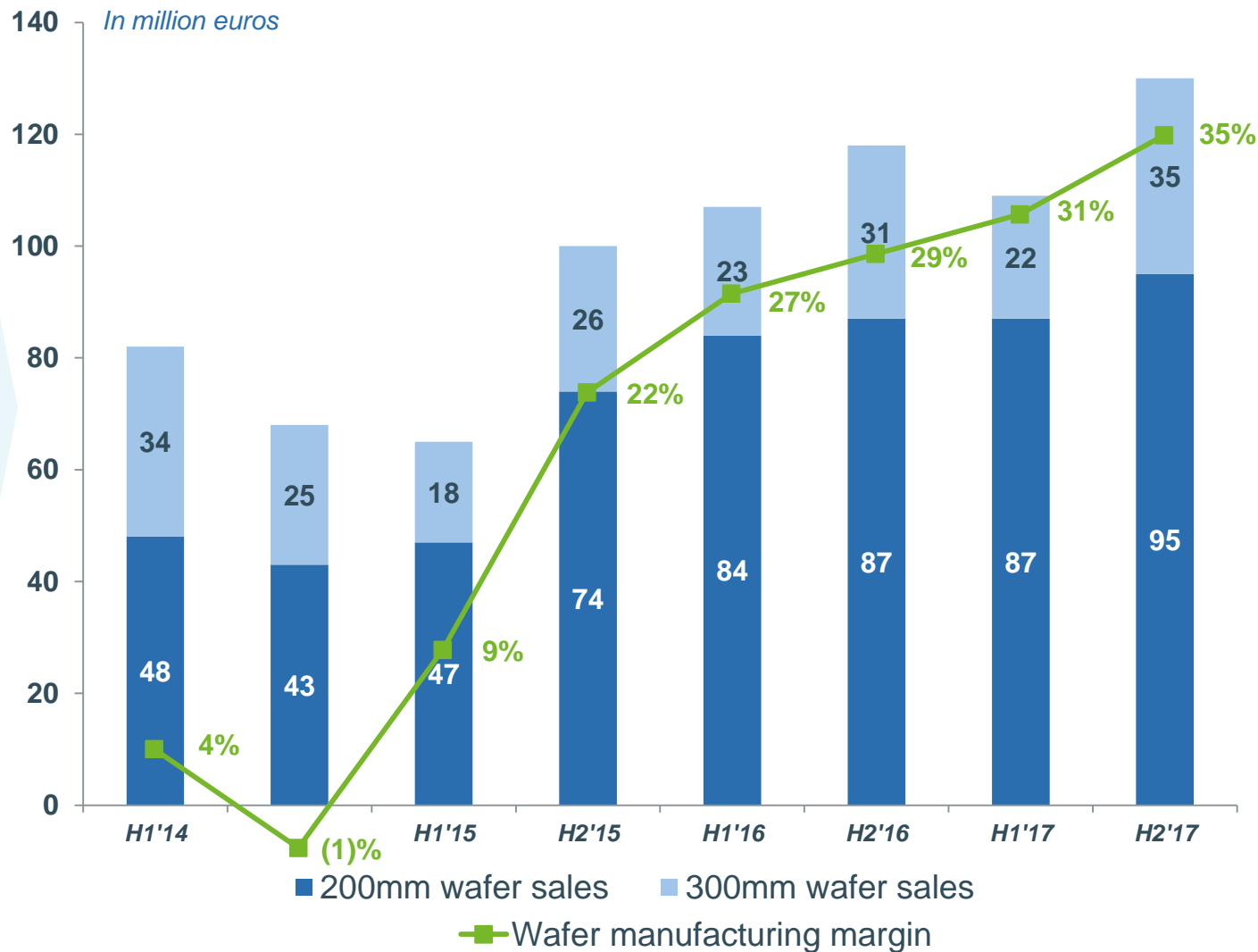
In million euros

	FY'17	FY'16 restated	Change
Sales	245.7	233.2	+5%
Gross profit <i>As a % of sales</i>	77.4 31.5%	62.2 26.7%	+24%
See detail on slide 13 Research and development expenses <i>As a % of sales</i>	(18.7) 7.6%	(16.7) 7.1%	+12%
See detail on slide 13 Selling, general and administrative expenses <i>As a % of sales</i>	(31.0) 12.6%	(23.2) 10.0%	+34%
Current operating income <i>As a % of sales</i>	27.7 11.3%	22.4 9.6%	+24%
EBITDA (Continuing operations) <i>As a % of sales</i>	41.0 16.7%	36.3 15.6%	+13%

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Continuous improvement in manufacturing margin

- 1 Steady revenue growth over the last quarters
- 2 200mm: industrial productivity further improved in Bernin I
- 3 300mm: increased utilization of Bernin II capacity in H2 (29% in Q4'17 vs low point of 14% in Q2'17)
- 4 Ongoing benefits from previous years cost saving plan



FY'17 operating expenses

R&D expenses (in million euros)	FY'17	FY'16 restated
Gross R&D expenses	(45.2)	(43.1)
Prototype sales and other	4.4	5.5
Subsidies and income tax credit	22.1	20.9
Total net R&D expenses	(18.7)	(16.7)
<i>As a % of sales</i>	<i>(7.6%)</i>	<i>(7.1%)</i>

SG&A expenses (in million euros)	FY'17	FY'16 restated
Sales & marketing expenses	(7.8)	(5.6)
General & administrative expenses	(23.2)	(17.7)
Total SG&A expenses	(31.0)	(23.2)
<i>As a % of sales</i>	<i>(12.6%)</i>	<i>(10.0%)</i>

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Group consolidated P&L (2/2)

In million euros

	FY'17	FY'16 restated
Current operating income	27.7	22.4
Other operating income and expenses	(8.2)	(29.4)
Operating income	19.5	(7.0)
See detail on slide 15 Net financial income/(expense)	(11.6)	(22.5)
Income tax	(0.7)	(4.1)
Net profit / (loss) from continuing operations	7.2	(33.6)
See detail on slide 16 Net profit / (loss) loss from discontinued operations	1.1	(38.7)
<hr/>		
Net profit / (loss) (Group share)	8.4	(72.2)

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FY'17 net financial result

In million euros

	FY'17	FY'16 Restated
Interest expense on OCEANE 2018	(4.7)	(10.2)
One-off charge related to the repurchase of OCEANE 2018	(2.2)	-
Interest expense on loans and credit lines	(0.8)	(3.3)
Interest expense on leasing	(1.1)	(1.3)
Non recurring financial expense	(0.6)	(0.4)
Other financial income / (expense)	(0.8)	(1.1)
Change in valuation of financial assets	1.2	(5.0)
Net financial income / (charges)	(9.1)	(21.4)
Net foreign exchange result	(2.5)	(1.1)
Net financial result	(11.6)	(22.5)

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Net profit from discontinued operations

Directly reported at the bottom of consolidated P&L

In million euros

	FY'17	FY'16 restated
Sales	0.8	26.8
Expenses	(0.6)	(35.0)
Current operating income/(loss)	0.2	(8.2)
Other operating income and expenses	(5.0)	(2.7)
Operating income/(loss)	(4.8)	(10.9)
Net financial income/(expense)	6.8	(27.1)
Income tax	(0.9)	(0.5)
Loss from equity affiliates	-	(0.2)
Net profit / (loss) from discontinued operations	1.1	(38.7)

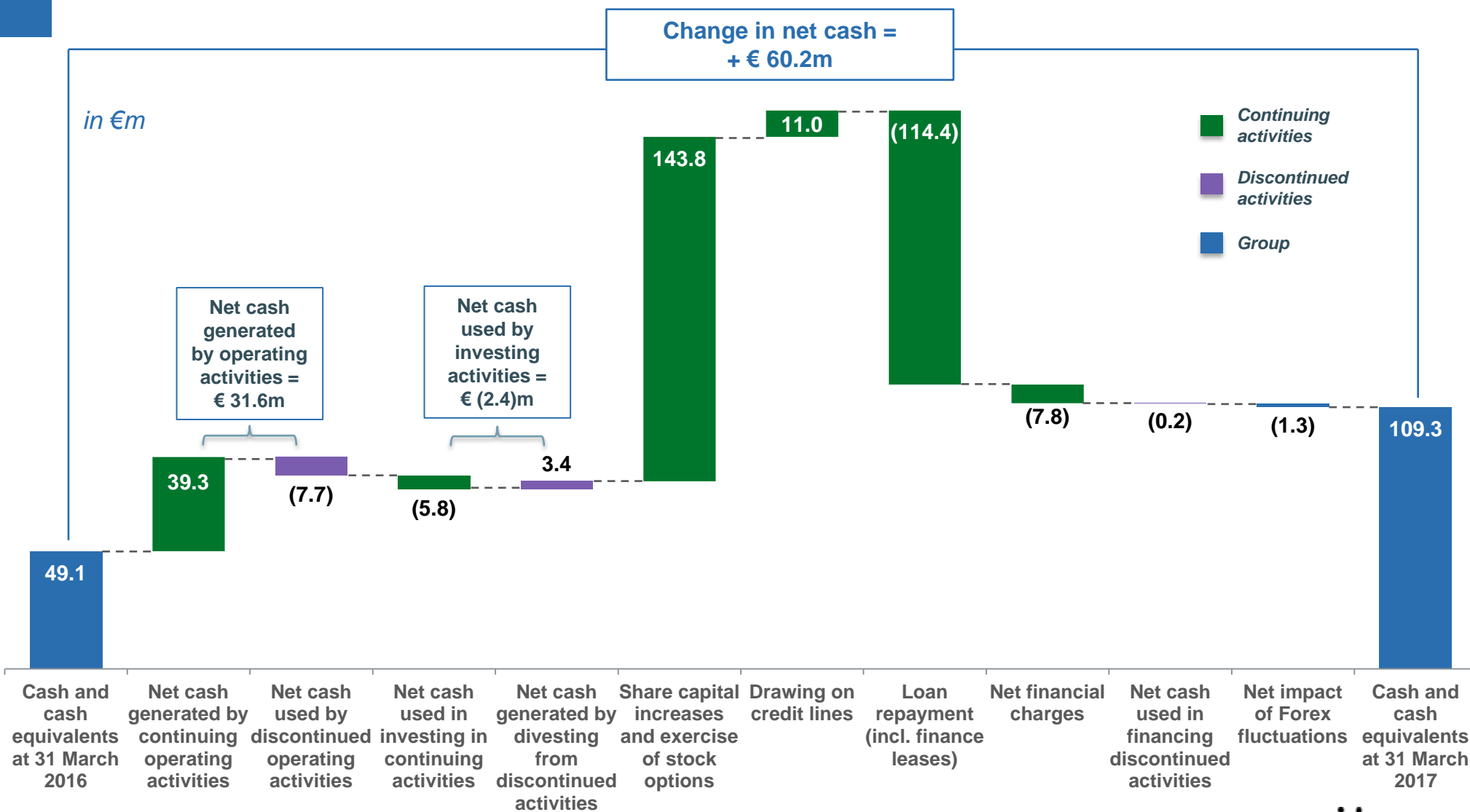
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FY'17 net cash generated by operating activities

In million euros

	FY'17	FY'16 restated
Net profit / (loss)	8.4	(72.2)
<i>of which continuing activities</i>	7.2	(33.6)
<i>of which discontinued activities</i>	1.1	(38.7)
Non cash items	23.8	50.1
<i>of which continuing activities</i>	33.8	69.9
<i>of which discontinued activities</i>	(10.0)	(19.8)
EBITDA	32.1	(22.1)
<i>of which continuing activities</i>	41.0	36.3
<i>of which discontinued activities</i>	(8.9)	(58.4)
Inventories	(4.0)	(5.2)
Trade receivables	1.4	(11.0)
Other receivables	(3.8)	(0.2)
Trade payables	2.8	(4.1)
Other liabilities	1.8	4.7
Change in working capital related to discontinued operations	1.2	25.6
Change in working capital	(0.6)	9.7
<i>of which continuing activities</i>	(1.7)	(15.9)
Net cash generated by operating activities	31.6	(12.5)
<i>of which continuing activities</i>	39.3	20.4
<i>of which discontinued activities</i>	(7.7)	(32.9)

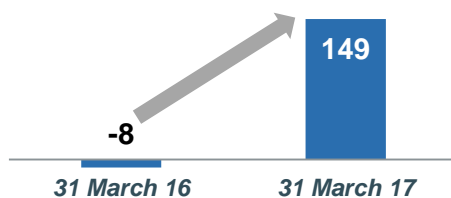
FY'17 strong cash generation



Major strengthening of the balance sheet during FY'17

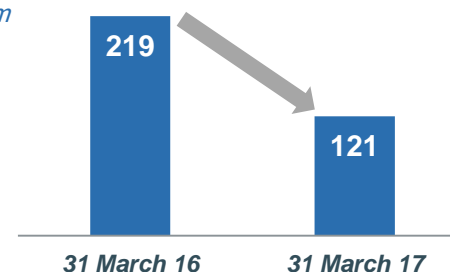
Shareholders' equity

in €m



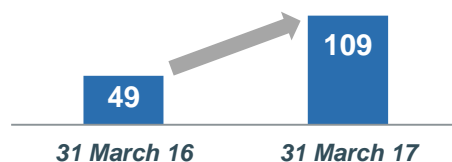
Gross debt

in €m



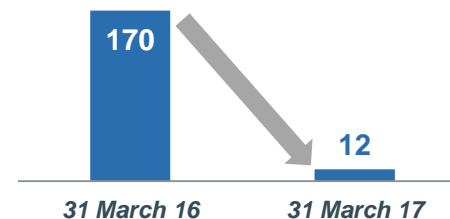
Cash and cash equivalents

in €m



Net debt

in €m



Simplified consolidated balance sheet

31 March 2017

In million euros

	31 March 2017	31 March 2016
Intangible assets	4.0	5.7
Tangible assets and other non current assets	157.0	154.2
Total non-current assets	161.0	159.9
Current assets	90.3	90.3
Cash and cash equivalents	109.3	49.1
Total current assets	199.6	139.4
Assets held for sale and discontinued	29.1	25.9
Total assets	389.6	325.1

In million euros

	31 March 2017	31 March 2016
Total equity	149.1	(7.9)
Long-term financial debt	104.7	160.0
Provisions and other non-current liabilities	15.2	14.1
Total non-current liabilities	119.8	174.1
Short-term financial debt	16.2	59.0
Current liabilities	90.7	83.4
Total current liabilities	106.9	142.4
Liabilities from discontinued operations	13.7	16.5
Total liabilities and equity	389.6	325.1

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1 FY'17 highlights

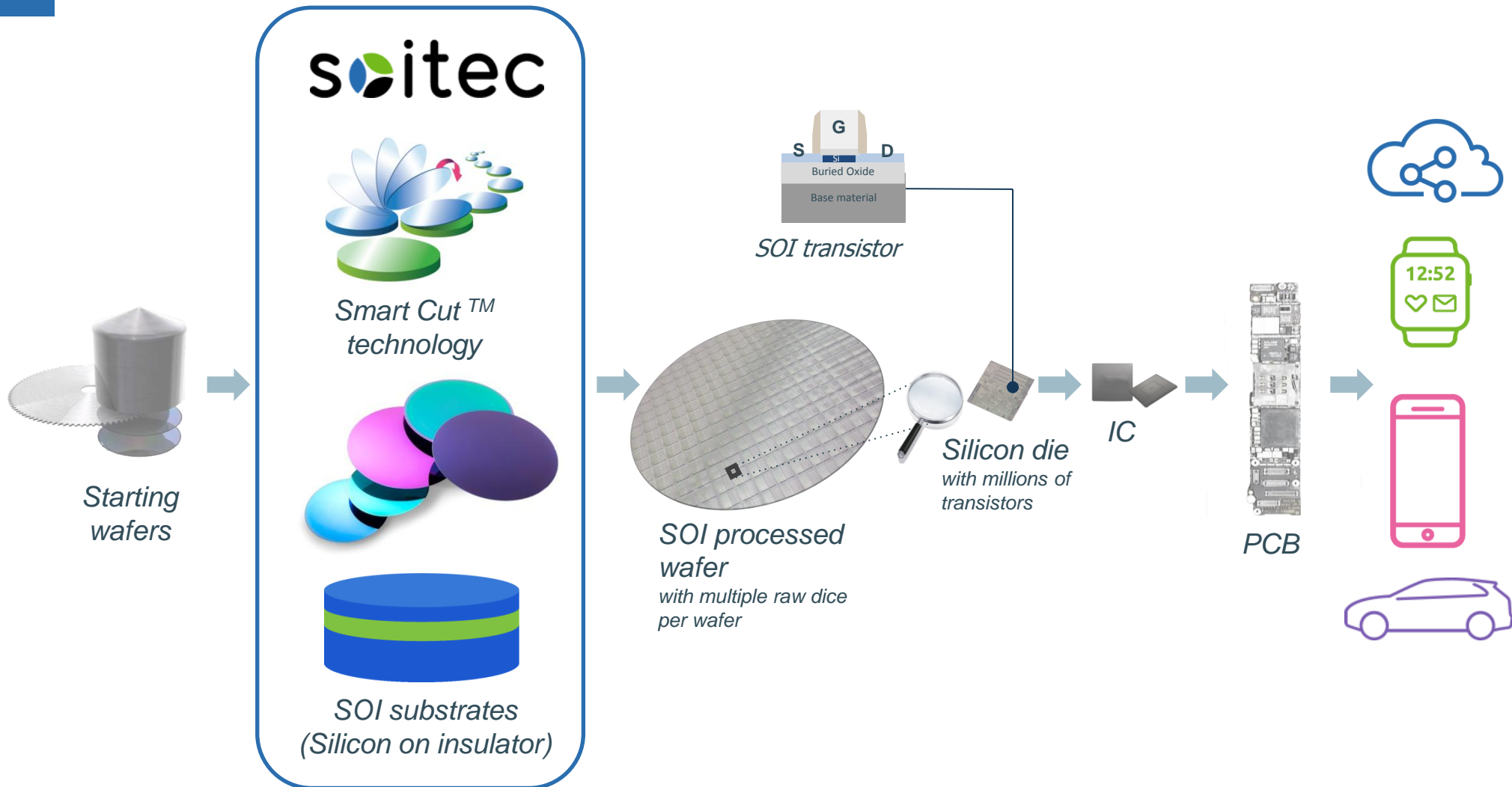
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Soitec in the value chain



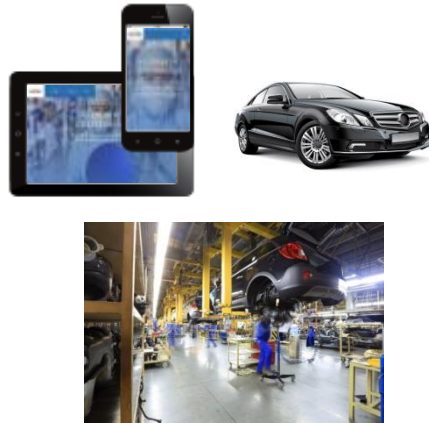
Soitec products well positioned in high growth markets today and tomorrow

2000-2010
PC, Gaming & Automobile



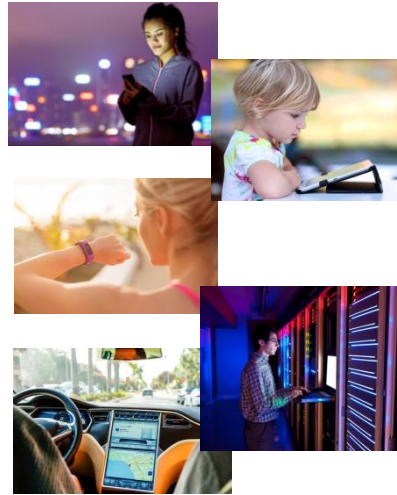
Main Soitec product: PD-SOI

SINCE 2010
Mobile, Automobile
& Industry



Main Soitec products: RF-SOI, Power-SOI

2017 +
Electronics for Everyday Use

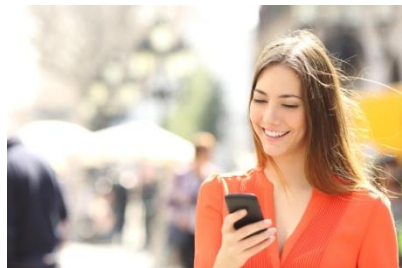


Main Soitec products: FD-SOI, RF-SOI, Power-SOI and other products to come

2020 +
5G World



Solutions addressing specific applications and markets



Smartphones

Semiconductors
requirements



IoT

Semiconductors
requirements



Automotive

Semiconductors
requirements



Data Center Cloud Computing

Semiconductors
requirements



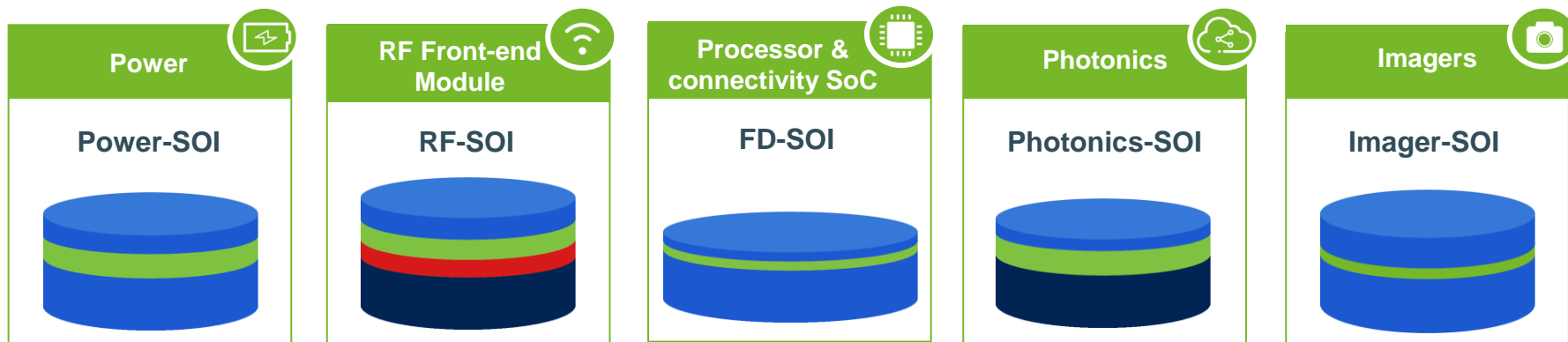
More performance

Lower power

High reliability

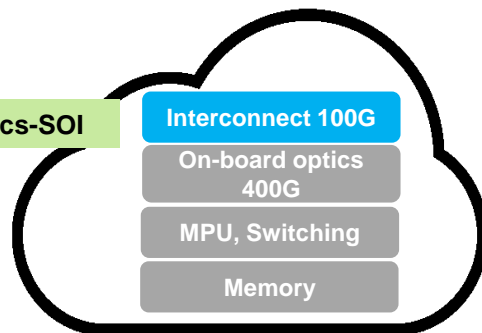
Lower cost

Soitec products addressing large markets with strong customer base

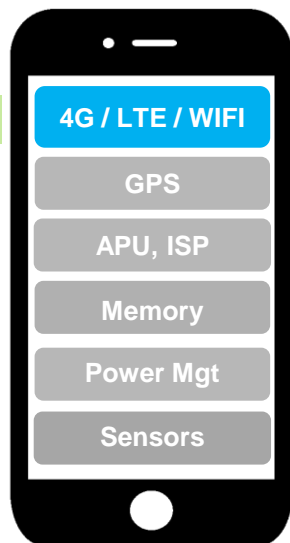


Soitec footprint FY'17

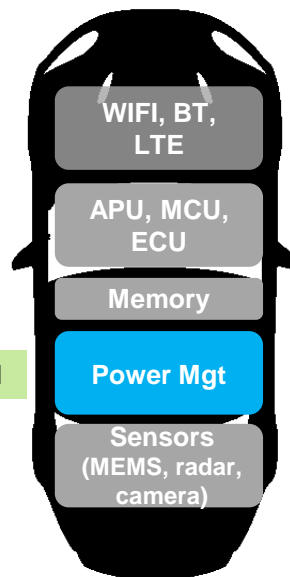
Photonics-SOI



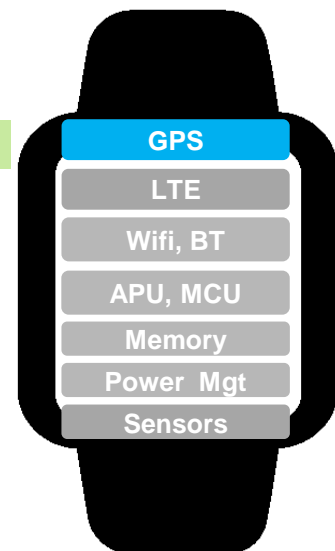
RF-SOI



Power-SOI



FD-SOI



RF-SOI is the standard addressing requirements of LTE/ 4G and 5G

Increased complexity to deliver higher data rates

2016 \longleftrightarrow 2021

3X higher data rate

2X more antennas

50X more carrier aggregation cases

Source : 3GPP

Growing RF-SOI content: migration to new LTE standards



Source : Soitec estimates, Navian April 2017

Value proposition

- › Enables Integration (switch, LNA, PA, passives)
- › Lowest cost vs. GaAs and MEMS technologies
- › Available in both 200 and 300mm

RF-SOI TAM (8" equivalent)



Source : Soitec estimates

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4G has long way to go

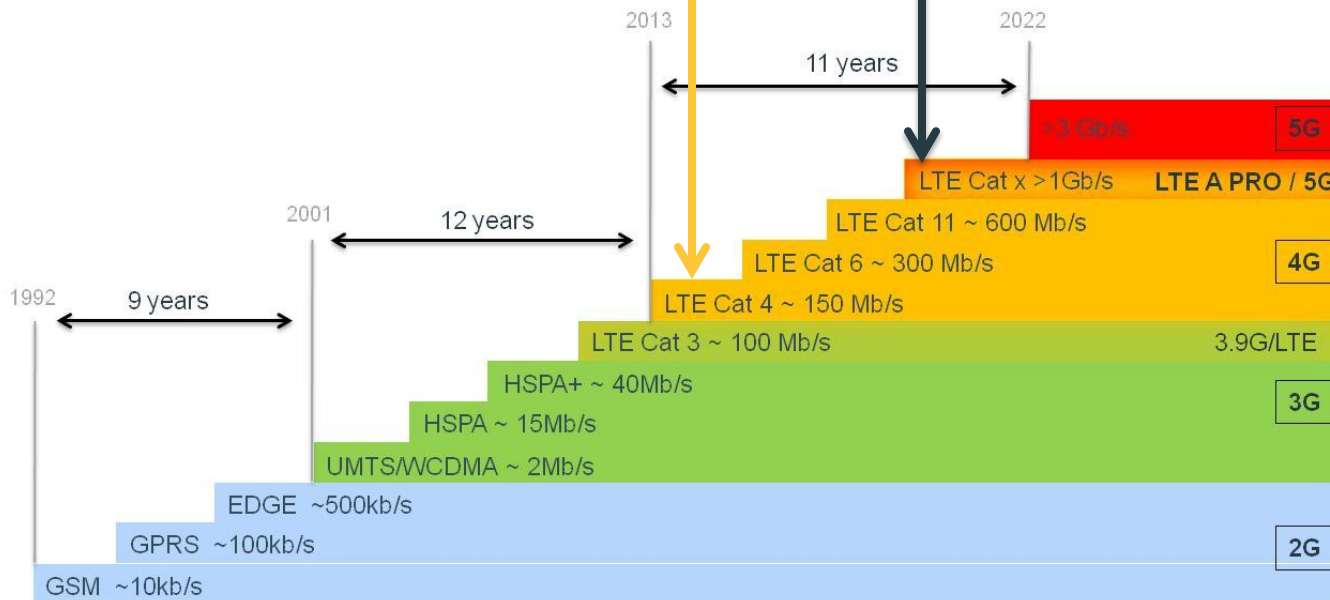
Most of 2017 phones are at lowest 4G specs only

Performance and Complexity Drive Content Opportunity

Complexity Factors Driving RF Content Expansion



Source: Skyworks Supplier Day, April 2017



Very strong RF roadmap for coming years will further grow RF-SOI content

Power-SOI

Semi content drivers for automotive and industrial applications

› More electronic content per vehicle

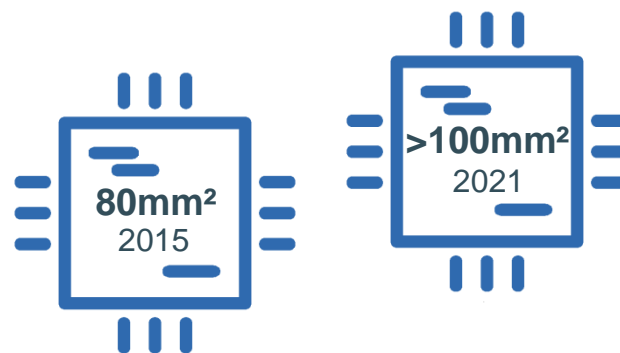
- › IVN network,
- › Safety,
- › Infotainment

› New energy efficiency standard

- › Next generation of “white goods”
- › Industrial applications

Power SOI content in automotive

Average SOI content in every car



Value proposition

- › High reliability
- › Automotive grade compatibility proven
- › Easy integration of different voltages
- › High temperature compatibility
- › Low Electro Magnetic Interference (EMI)

Power SOI TAM (8” equivalent)



Source : Soitec estimates

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FD-SOI brings huge differentiation in mobile, IoT, 5G & automotive markets

Mobility

Best Power/Perf/Cost solution for

- › Low-mid tier **Baseband + AP**
- › **4G** transceiver integration
- › **5G** mmWave design



IoT

Perfect fit for wireless & ULP / ULL IoT clients in need of :

- › On-demand processing performance
- › Integrated RF
- › Embedded memory



5G & Radars

Ideal technology for

- › **5G mmWave** low power single chip solution with integrated PA
- › **<6GHz** applications w/ 35-50% die shrink (LTE, Wifi,...)



Automotive

Unique advantages in low power/ high reliability (SER)

- › **ADAS** (<5W) for autonomous driving
- › **Radar** - Mid to long range single chip
- › **Infotainment**
- › **MCU** for Body Electronics



FD-SOI global wafers estimate:

› 2021 (est.): 1-3M wafers/y.

Source : Soitec estimates

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The FD-SOI revolution has started in consumer & automobile

Consumer: a game changer technology for better battery life

- › FD-SOI technology unlocks battery-powered device potential



- › FD-SOI based Sony GPS to cut standard **GPS power consumption by 5 to 10x**
- › Now, more than a day autonomy with GPS ON



- › i.MX based reference platform developed by NXP for **Amazon's Alexa**
- › FD-SOI is a key enabler of the i.MX reference platform for **always-on applications**

Automotive : best power efficiency allowing simpler integration and enhanced reliability

- › FD-SOI - reference technology for ADAS level 3 applications
- › Next generation e-Cockpit solution with full management of car infotainment



- › **Level 3 autonomous driving**
- › **2.5Tops @ only 3W**



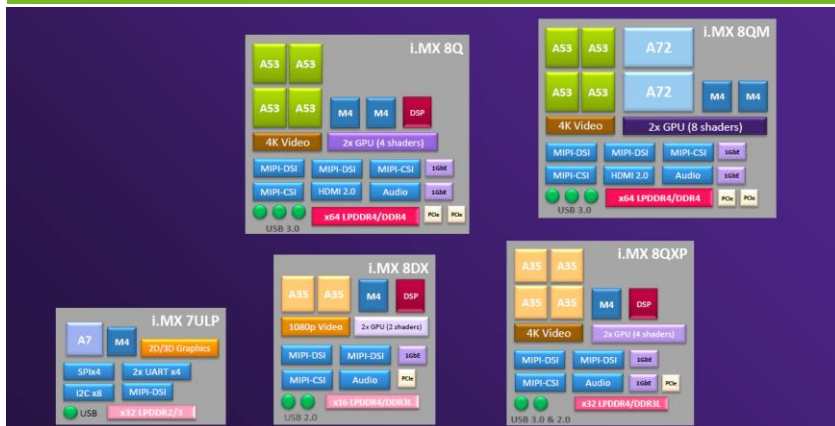
- › Advanced features - **object recognition** through neural network

i.MX 8 series
Advanced Graphics & Performance
ARM® v8-A



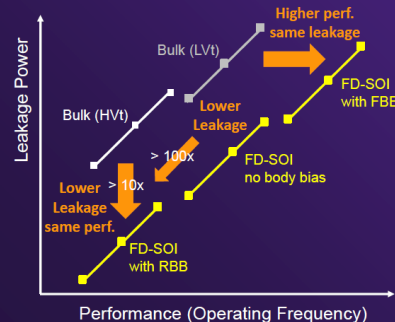
NXP – First mass multi-market FD-SOI adoption

From very simple (IoT) to very complex (automotive) devices



Ability to adjust performance and power consumption

FD-SOI Enabling Wide Dynamic Operating Range



- Outstanding Power-Perf demonstrated
 - Active mode @ 300MHz < 10mW
 - Deep-sleep with SRAM retained: < 2.5μW
 - Extremely low-leakage SRAM: ~ 0.5pA/bit
- Forward Body Bias (FBB) Expanded performance
- Reverse Body Bias (RBB) Lower leakage floor
- Dynamic biasing tunability - SoC & part-by-part

Flexible platform integrating key functionalities

FD-SOI: Process Technology for the Next-Generation IoT



Source: NXP presentation at SOI Consortium, Santa Clara, April 2017

FD-SOI – A mainstream solution with many choices

Performance & density at any cost - for Servers, networking & High-end Mobile

FinFET
7nm

FinFET
10 nm

FinFET
16/14nm

HK,
PolySi
28nm

Bulk
90/65/45
nm

Cost-effective & performance for Low-power applications

FD-SOI
12 nm

FD-SOI
18 nm

FD-SOI
22 nm

FD-SOI
28 nm

FD-SOI
65 nm

eMRAM

eMRAM

eMRAM



FD-SOI: ecosystem getting stronger

A rapidly growing FD-SOI ecosystem

Research Technology & IP



leti



SAMSUNG



Substrates

soitec

& Licensees

Tools & EDA

SYNOPSYS®

KEYSIGHT TECHNOLOGIES

Mentor Graphics

cadence™

Foundries&IDM



RENESAS

SAMSUNG



life.augmented

IP & Design Services

surecore

ARM

invecas

alchip

IMAGINATION

VeriSilicon

SILVACO

SYNAPS design

QIALCHIP

Open-Silicon

Your Idea. Delivered.™

Fabless & OEMs

SONY

NXP

clena

MOBILEYE

SFARDS

eSilicon

CISCO

Dream CHIP

+50 fabless under development

Consumer Products



Latest Announcements

GLOBALFOUNDRIES

- ✓ GLOBALFOUNDRIES and the Chengdu municipality to invest 100M\$ to build a world-class FD-SOI ecosystem including multiple design centers and accelerate adoption of 22 FD-SOI (FDX) in China
- ✓ Increasing 22 FD-SOI capacity: +40% est. in Germany by 2020
New 300 mm fab. in China with expected volume production in 2019
- ✓ Focus on 12 FD-SOI development

SAMSUNG

- ✓ Extension of current 28 nm FD-SOI platform by incorporating RF and embedded MRAM
- ✓ 18 nm FD-SOI process technology targeted for risk production in 2019

CEA - LETI

- ✓ Presented path to 10nm FD-SOI

IP/ EDA Vendors

- ✓ Active position in promoting FD-SOI

Emerging SOI for Data Centers and Imager markets

CISCO
100G LR4 CPAK



Silicon Photonics

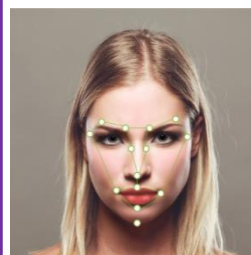
Growth drivers

- › 100Gb Ethernet interconnection standard in data centers
- › High speed interconnection of ASIC
- › Solution integrated in CMOS fab to enable high volume/low cost

SOI Value proposition

- › Mainstream technology for silicon photonics devices
- › 200mm and 300mm compatible
- › Predefine optical waveguide embedded into a silicon wafer CMOS compatible

INTEL
100G CWDM4 QSFP28



Imagers

Growth drivers

- › Next generation imagers for:
 - › Enhanced augmented & virtual reality experience
 - › Facial recognition
 - › Gesture recognition
 - › 3D printing

SOI Value proposition

- › Substrate based noise cancellation solution
- › Near-IR sensor gains :
 - › Dark current removal
 - › Increased Signal/Noise ratio
 - › Increased resolution

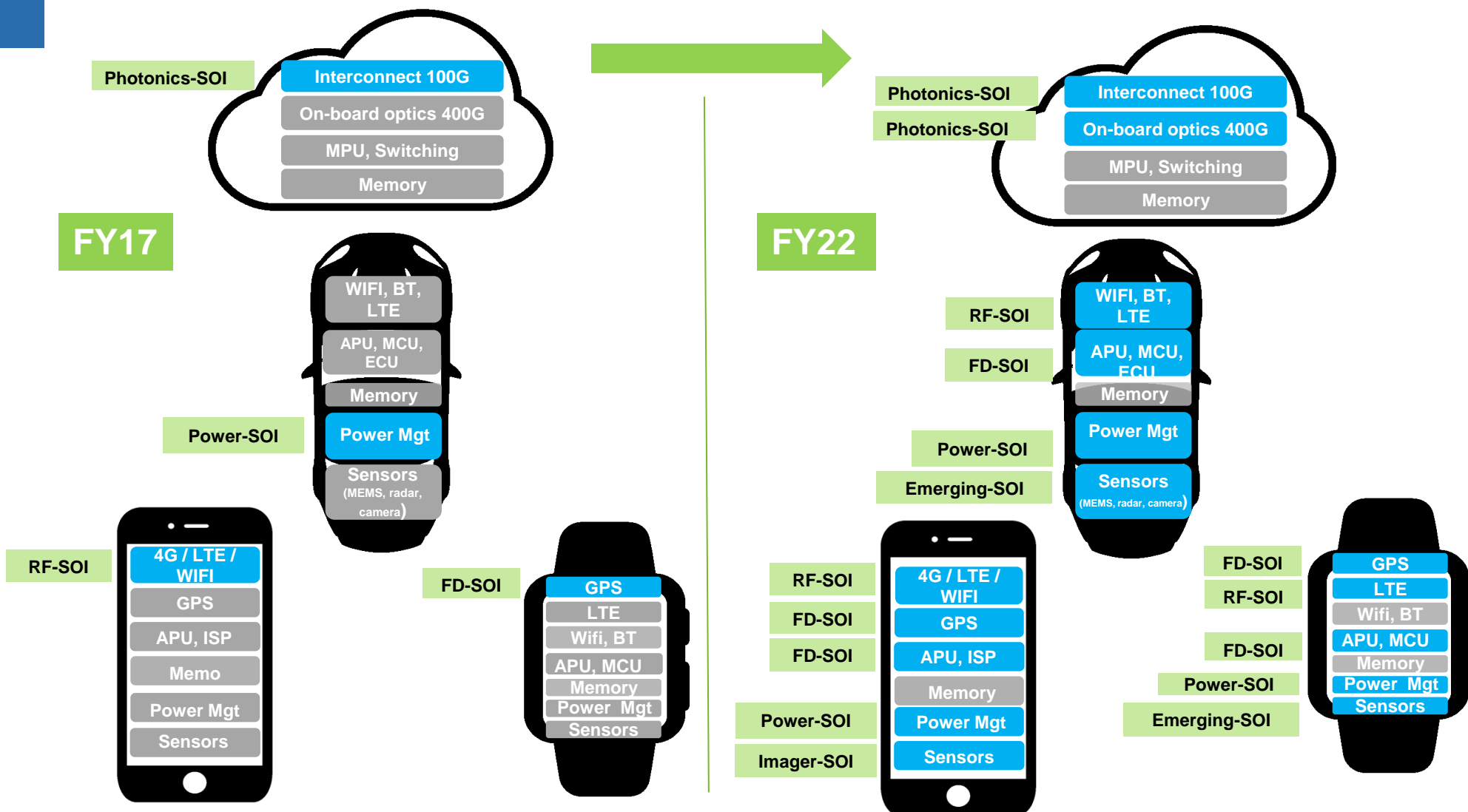


Emerging SOI Global Wafers Estimates

› 2016 : 15-30 K wafers

› 2021 (est.): 100-300 K wafers

Soitec products growing adoption in 4 strategic end-markets



Agenda

- 1 FY'17 highlights
- 2 FY'17 financials
- 3 Business review: promising prospects in Electronics
- 4 Outlook**
- 5 Appendix

Soitec global manufacturing capacity

soitec
300mm SOI

Soitec Bernin II, France
HVM



650 kwfrs/yr capacity
of which FD-SOI capacity will be
increased from 100 kwfrs to
400kwfrs

Total potential 300mm
capacity =
Up to 1.5 Mwfrs/yr



Pasir Ris, Singapore
Ready HVM



+ 800 kwfrs/yr capacity
(Investment decision pending)

soitec
200mm SOI

Soitec Bernin I, France
HVM



850 kwfrs/yr capacity

Singui, China
Ramp to HVM



75 kwfrs/yr capacity
to be raised to 150 kwfrs/yr by
FY'19

Total 200mm
capacity =
1 Mwfrs/yr by
FY'19

Capex

› Decision to go ahead with Bernin II capex has been made

- › € 40m long-planned investment at Bernin II to be spread between FY'18 and FY'19
- › Process has actually started - first part of capex already incurred
- › Cash at hand
- › Will progressively boost Bernin II FD-SOI production capacity from 100k wafers to 400k wafers per year

› Intention to invest in the reopening of Singapore plant

- › Opportunity to reopen Singapore 300mm plant that would be primarily dedicated to FD-SOI
- › Net restarting cost for Soitec would amount to approx. € 20m to be spread over 24 months
- › Total contemplated investment would reach approx. US\$ 270m to bring production capacity up to 800k wafers per year
 - Capex to include a qualification line worth US\$ 40m to be spent over 24 months following decision
 - Customer commitments to trigger the gradual roll out of capex
- › All financing options are currently being considered, with the choice likely to be determined by the timing of the investment

FY'18 Guidance

› FY'18 sales expected to grow by around 25% at constant exchange rates

- › Demand remains robust for RF-SOI products driven by the growing adoption of LTE Advanced standard in the new generation of smartphones
- › Sustained demand for Power-SOI products to be maintained, driven by automotive and “white goods” applications
- › 300mm business expected to continue recovering from the low point reached in Q2'17 with further growth coming from new products (RF-SOI, FD-SOI, Emerging SOI) more than offsetting lower PD-SOI

› FY'18 Electronics EBITDA margin⁽¹⁾ expected to reach a minimum of 20%

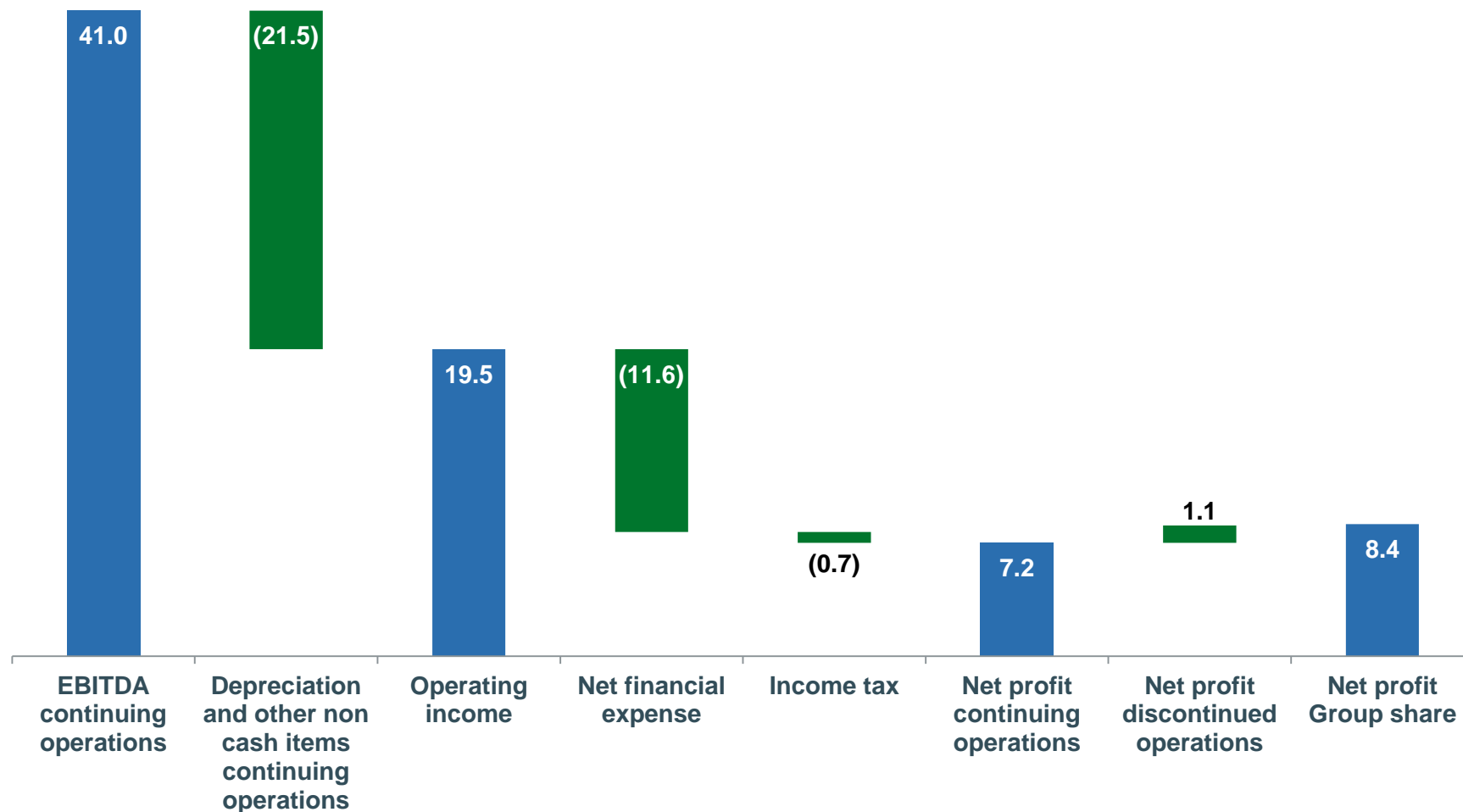
- › Sustained operating profitability to be maintained at Bernin I which is expected to continue to operate at full capacity
- › Higher operating leverage expected at Bernin II with a utilization rate that should reach around 50% of capacity towards the end of FY'18 / early FY'19

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FY'17 – from Electronics EBITDA to net profit

In million euros



FY'17 cash flow statement

In million euros

	FY'17	FY'16 restated
Net cash generated by / (used in) operating activities	31.6	(12.5)
<i>of which continuing activities</i>	39.3	20.4
Net cash generated by / (used in) investing activities	(2.4)	26.9
<i>of which continuing activities</i>	(5.8)	(7.3)
Share capital increases and exercise of stock options	143.8	(0.1)
ABSAAR buyback (warrant cancellation)	-	(0.7)
Issuance of debt (new loans)	-	65.4
Drawing on credit lines	11.0	0.9
Loan repayment (incl. finance leases)	(114.4)	(23.0)
Net financial charges	(7.8)	(9.2)
Financing flows from discontinued operations	(0.2)	(21.0)
Net cash generated by / (used in) financing activities	32.4	12.4
<i>of which continuing activities</i>	32.6	33.3
Impact of exchange rate fluctuations	(1.3)	(0.7)
Change in net cash	60.2	26.2
<i>of which continuing activities</i>	64.8	45.7
Cash & cash equivalents - opening	49.1	22.9
Cash & cash equivalents - closing	109.3	49.1

Consolidated balance sheet

31 March 2017

<i>In million euros</i>	31 March 2017	31 March 2016
Goodwill and intangible assets	2.5	3.8
Capitalized development projects	1.5	1.9
Property, plant and equipment	113.5	120.6
Non-current financial assets	12.2	8.9
Other non-current assets	31.3	24.7
Total non-current assets	161.0	159.9
Inventories	33.6	30.9
Trade receivables	40.0	40.4
Other current assets	14.8	17.5
Current financial assets	1.8	1.4
Cash and cash equivalents	109.3	49.1
Total current assets	199.5	139.4
Assets held for sale and discontinued	29.1	25.9
Total assets	389.6	325.1

<i>In million euros</i>	31 March 2017	31 March 2016
Share capital	60.6	23.1
Share premium	887.5	780.4
Reserves	(799.0)	(811.4)
Total equity	149.1	(7.8)
Long-term financial debt	104.7	160.0
Provisions and other non-current liabilities	15.2	14.1
Total non-current liabilities	119.8	174.1
Short-term financial debt	16.2	59.0
Trade payables	44.4	42.6
Provisions and other current liabilities	46.3	40.8
Total current liabilities	106.9	142.4
Liabilities from discontinued operations	13.7	16.5
Total liabilities and equity	389.6	325.1

Smartphones – Our #1 end market (~60% of revenues)

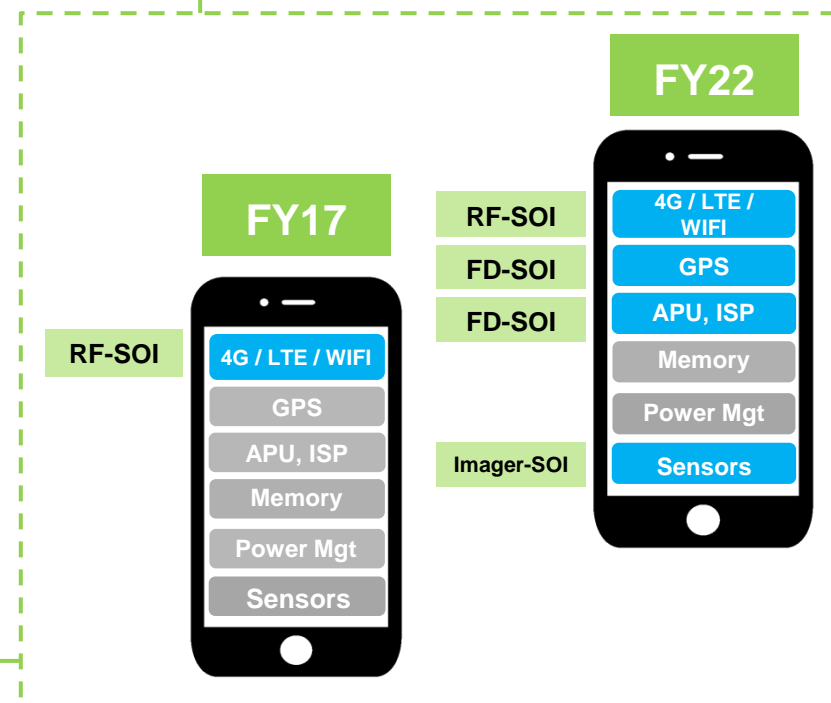
› Solid growth drivers for RF front-end modules

- › **RF-SOI products** established as the standard solution for antenna switches
- › Semiconductor content to increase with the number of aggregated bands and design complexity
- › 5G opportunities with “mmWave” to enable larger data bandwidth and faster content delivery



› New Soitec products to bring additional revenue opportunities

- › **FD-SOI** for low/mid-entry application processors and baseband integrated circuits, image signal processors, RF transceivers
- › **Imagers-SOI** for advanced image sensors (3D gesture, facial recognition, AR/VR, etc.)
- › **New engineered substrates materials** (piezo, compounds) for RF-FEM



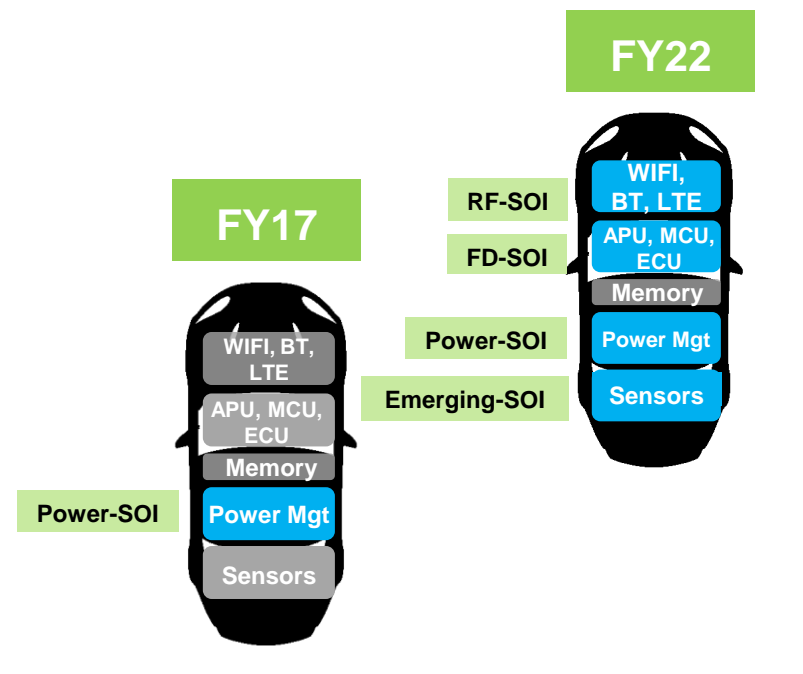
Automotive – 2nd largest end market (~20% of revenues)

› Overall semiconductor content for automotive continues to increase

- › Semiconductors enable 80% of innovation in automotive
- › Annual content increase (mid-single digit) driven by electric vehicles, infotainment, autonomous driving, etc.

› Soitec revenue growth fuelled by existing and new products

- › **Power-SOI (legacy product line)** for transceivers (in-vehicle networking) used for electronic control units, amplifiers (audio) for infotainment, gate drivers for power train
- › **FD-SOI** for cars autonomous driving (vision processors, radars) and application processors for infotainment
- › **RF-SOI** for vehicle-to-infrastructure, vehicle-to-vehicle
- › **New engineered substrates for sensors** (MEMS, imaging)



Internet of Things (IoT) – Growing opportunities, multiple verticals

› IoT offers multiple growth opportunities

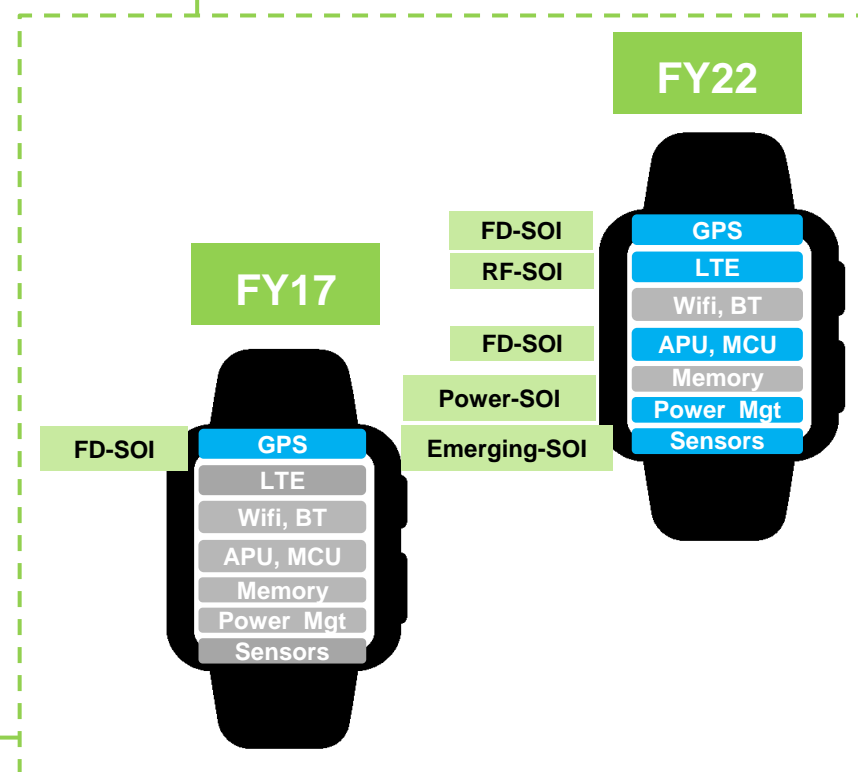
- › **Many consumer or industrial applications:** smartwatch, fitness trackers, drones, head-mounted displays, Industry 4.0 devices, etc.
- › Large semiconductor opportunity with high level of integration: digital, connectivity, sensors, etc.

› Soitec existing and new products portfolio to address several verticals

- › **FD-SOI** for wireless and battery-powered devices that require ultra-low power and ultra-low leakage (always-on); also compatible with non-volatile memories and artificial intelligence modules
- › **RF-SOI** for front-end module integration for ultra-low power communication; opportunities for cellular standards such as NB-IoT, LTE-cat1,...
- › **New engineered substrates materials** for sensors (MEMS, imaging)







amazon alexa



Datacenters, Cloud computing – Revolution is underway

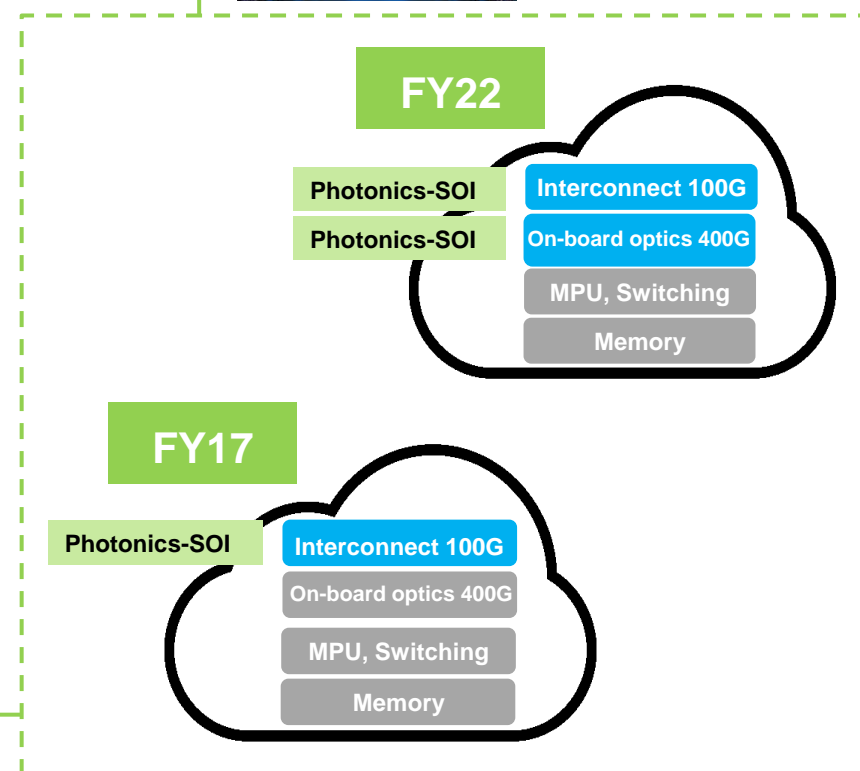
› Major growth driver: data traffic

		2015	2020
More Internet Users		3.0 Billion	4.1 Billion
More Devices & Connections		16.3 Billion	26.3 Billion
Faster Broadband Speeds		24.7 Mbps	47.7 Mbps
More Video Viewing		70% of Traffic	82% of Traffic

Source: Cisco VNI Global IP Traffic Forecast, 2015–2020

› Soitec products to enable disruption in computing and interconnect technologies

- › Photonics-SOI for high speed transceivers
- › FD-SOI to support the power consumption challenge of server related ASICs



Thank you



Steve.babureck@soitec.com

Steve Babureck,
Investor Relations Officer



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